L Number	Hits	Search Text	DB	Time stamp
•	280	((ball or solder) near5 completely near5	USPAT;	2002/12/19
		(remove or removing or removed or etch or	US-PGPUB;	14:58
		etched or etching or clean or cleaning or	EPO; JPO;	
		cleaned))	DERWENT;	
		<i>"</i>	IBM_TDB	
•	18	((ball or solder) near completely near	USPAT;	2002/12/19
		(remove or removing or removed or etch or	US-PGPUB;	14:54
		etched or etching or clean or cleaning or	EPO; JPO;	
		cleaned))	DERWENT;	
			IBM_TDB	
-	49	(((ball or solder) near5 completely near5	USPAT;	2002/12/19
	40	(remove or removing or removed or etch or	US-PGPUB;	14:55
		etched or etching or clean or cleaning or	EPO; JPO;	14.00
		cleaned))) and (etch or etching or etched)	DERWENT;	
		creaneu))) and teten or etening or eteneu)		
			IBM_TDB	0000/40/40
•	26	((((ball or solder) near5 completely near5	USPAT;	2002/12/19
		(remove or removing or removed or etch or	US-PGPUB;	14:55
		etched or etching or clean or cleaning or	EPO; JPO;	
		cleaned))) and (etch or etching or etched))	DERWENT;	
		and semiconductor	IBM_TDB	
•	8	((resin or coat or coating or epoxy) near5	USPAT;	2002/12/19
		completely near5 (remove or removing or	US-PGPUB;	15:02
		removed or etch or etched or etching or	EPO; JPO;	
		clean or cleaning or cleaned) near5 (solder	DERWENT;	
		or ball or bump))	IBM_TDB	
•	7	((resin or coat or coating or epoxy) near10	USPAT;	2002/12/19
		completely near10 (remove or removing or	US-PGPUB;	15:19
		removed or etch or etched or etching or	EPO; JPO;	
		clean or cleaning or cleaned) near10 (solder	DERWENT;	
		or ball or bump)) and semiconductor	IBM_TDB	
	11	((resin or coat or coating or epoxy) near20	USPAT;	2002/12/19
		completely near20 (remove or removing or	US-PGPUB;	15:14
		removed or etch or etched or etching or	EPO; JPO;	10.14
		clean or cleaning or cleaned) near20 (solder	DERWENT;	
		or ball or bump)) and semiconductor	IBM_TDB	
			_	2002/42/40
	0	((resin or epoxy) near5 (ball or bump) near5	USPAT;	2002/12/19
		completely near5 (remove or removing or	US-PGPUB;	15:27
		removed or etch or etching or etched or	EPO; JPO;	
		clean or cleaning or cleaned)) and	DERWENT;	
	_	semiconductor	IBM_TDB	
•	3	((resin or epoxy) near10 (ball or bump)	USPAT;	2002/12/19
		near10 completely near10 (remove or	US-PGPUB;	15:30
		removing or removed or etch or etching or	EPO; JPO;	
		etched or clean or cleaning or cleaned))	DERWENT;	
		and semiconductor	IBM_TDB	
-	6	((resin or epoxy) near30 (ball or bump)	USPAT;	2002/12/19
		near30 (completely or fully) near30 (remove	US-PGPUB;	15:34
		or removing or removed or etch or etching	EPO; JPO;	
		or etched or clean or cleaning or cleaned))	DERWENT;	
		and semiconductor	IBM_TDB	

	1	<u> </u>		r
-	7515	(resin or epoxy) near2 (ball or solder or	USPAT;	2002/12/19
}		bump)	US-PGPUB;	15:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	20	((resin or epoxy) near2 (ball or solder or	USPAT;	2002/12/19
		bump)) near5 (completely or fully)	US-PGPUB;	15:38
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	4	((resin or epoxy) near2 (ball or solder or	USPAT;	2002/12/19
		bump)) near5 (completely or fully) and	US-PGPUB;	15:39
		semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
l <u>-</u>	7	((resin or epoxy) near2 (ball or solder or	USPAT;	2002/12/19
	•	bump)) near10 (completely or fully) and	US-PGPUB;	15:40
		semiconductor	EPO; JPO;	10.40
		30 mileonauctor	DERWENT:	
			IBM TDB	
	39	((resin or epoxy) near5 (ball or solder or	_	2002/12/19
_	39	, ,	USPAT;	15:50
		bump)) near20 (completely or fully) and	US-PGPUB;	15:50
		semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	330	(resin or epoxy) near5 (ball or solder) near5	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	15:52
		etching or etched or clean or cleaned or	EPO; JPO;	
		cleaning)	DERWENT;	
			IBM_TDB	
-	3	((resin or epoxy) near (ball or solder) near	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	15:54
		etching or etched or clean or cleaned or	EPO; JPO;	
		cleaning)) and semiconductor	DERWENT;	
			IBM_TDB	
-	109	((resin or epoxy) near5 (ball or bump) near5	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	15:56
		etching or etched or clean or cleaned or	EPO; JPO;	
		cleaning)) and semiconductor	DERWENT;	
			IBM_TDB	
-	22	((resin or epoxy) near2 (ball or bump) near2	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	16:02
1		etching or etched or clean or cleaned or	EPO; JPO;	
	1	cleaning)) and semiconductor	DERWENT;	
			IBM_TDB	
-	4	(((resin or epoxy) near5 (ball or bump) near5	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	15:59
		etching or etched or clean or cleaned or	EPO; JPO;	
		cleaning)) near20 (completely or fully)) and	DERWENT;	
		semiconductor	IBM_TDB	
	<del> </del>			

-	5	(((resin or epoxy) near5 (ball or bump) near5	USPAT;	2002/12/19
		(remove or removed or removing or etch or	US-PGPUB;	16:02
	1	etching or etched or clean or cleaned or	EPO; JPO;	
		cleaning)) same (completely or fully)) and	DERWENT;	
		semiconductor	IBM_TDB	
-	6	(((resin or epoxy) near10 (ball or bump)	USPAT;	2002/12/19
		near10 (remove or removed or removing or	US-PGPUB;	16:04
		etch or etching or etched or clean or	EPO; JPO;	
	1	cleaned or cleaning)) same (completely or	DERWENT;	
		fully)) and semiconductor	IBM_TDB	
-	89	((resin or epoxy) near (completely or fully)	USPAT;	2002/12/19
		near (remove or removing or removed or	US-PGPUB;	16:08
		etch or etched or etching or clean or	EPO; JPO;	
		cleaning or cleaned))	DERWENT;	
			IBM_TDB	
-	2	(((resin or epoxy) near (completely or fully)	USPAT;	2002/12/19
		near (remove or removing or removed or	US-PGPUB;	16:08
		etch or etched or etching or clean or	EPO; JPO;	
		cleaning or cleaned))) and (bump or ball)	DERWENT;	
		and semiconductor	IBM_TDB	
-	1994	((resin or epoxy) near10 (completely or	USPAT;	2002/12/19
		fully) near10 (remove or removing or	US-PGPUB;	16:08
		removed or etch or etched or etching or	EPO; JPO;	
		clean or cleaning or cleaned))	DERWENT;	
			IBM_TDB	
-	60	(((resin or epoxy) near10 (completely or	USPAT;	2002/12/19
		fully) near10 (remove or removing or	US-PGPUB;	16:09
		removed or etch or etched or etching or	EPO; JPO;	
		clean or cleaning or cleaned))) and (bump	DERWENT;	
		or ball) and semiconductor	IBM_TDB	
-	35	((((resin or epoxy) near10 (completely or	USPAT;	2002/12/19
		fully) near10 (remove or removing or	US-PGPUB;	16:09
		removed or etch or etched or etching or	EPO; JPO;	
		clean or cleaning or cleaned))) and (bump	DERWENT;	
		or ball) and semiconductor) and ((bump or	IBM_TDB	
		ball) near10 (epoxy or resin))	_	
-	4500	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
			US-PGPUB;	19:09
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1340	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
	[	and (resin near (coat or coating or	US-PGPUB;	19:09
}		coated)).ab.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	51	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
		and (resin near (coat or coating or	US-PGPUB;	19:09
		coated)).ab. and (board or pcb ).ab.	EPO; JPO;	
		· · ·	DERWENT;	
			IBM_TDB	

-	45	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
		and (resin near (coat or coating or	US-PGPUB;	19:09
		coated)).ab. and (board or pcb ).ab. and	EPO; JPO;	
		(board or pcb).clm.	DERWENT;	
			IBM_TDB	
-	5	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
		and (resin near (coat or coating or	US-PGPUB;	19:10
		coated)).ab. and (board or pcb ).ab. and	EPO; JPO;	
		(board or pcb).clm. and (bump or ball).clm.	DERWENT;	
			IBM_TDB	
-	5	((ball or bump) near resin near (coat or	USPAT;	2004/02/20
		coating or coated)).clm.	US-PGPUB;	19:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4500	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
			US-PGPUB;	19:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5	((bump or ball) near resin near (coat or	USPAT;	2004/02/20
		coating or coated)).clm.	US-PGPUB;	19:33
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	10	((bump or ball) near2 resin near2 (coat or	USPAT;	2004/02/20
		coating or coated)).clm.	US-PGPUB;	19:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	45	((bump or ball) near5 resin near5 (coat or	USPAT;	2004/02/20
		coating or coated)).clm.	US-PGPUB;	19:35
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	38	((bump or ball) near5 resin near5 (coat or	USPAT;	2004/02/20
		coating or coated)) and adhesive and	US-PGPUB;	19:35
		((metal or gold or silver) near (bump or	EPO; JPO;	
		ball))	DERWENT;	
			IBM_TDB	
-	20	((bump or ball) near5 resin near5 (coat or	USPAT;	2004/02/20
		coating or coated)) and adhesive and	US-PGPUB;	19:37
		((metal or gold or silver) near (bump or	EPO; JPO;	
		ball)) and ((metal or gold or silver) near	DERWENT;	
		(layer or foil or film))	IBM_TDB	
•	15	((bump or ball) near10 resin near10 (coat or	USPAT;	2004/02/20
		coating or coated)) and adhesive and	US-PGPUB;	19:37
	[	((metal or gold or silver) near (bump or	EPO; JPO;	
		ball)) and ((metal or gold or silver) near	DERWENT;	
L	L	(layer or foil or film)) and (board or pcb)	IBM_TDB	

	11	bump.clm. and anam	USPAT;	2004/02/20
-	ı	bump.cmi. and anam	US-PGPUB;	19:39
				13:33
			EPO; JPO;	
i			DERWENT;	
			IBM_TDB	
-	129	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)).clm. and ((metal or gold or silver)	US-PGPUB;	19:40
		near2 (ball or bump))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	62	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
	•	coated)).clm. and ((metal or gold or silver)	US-PGPUB;	19:40
		near2 (ball or bump)).clm.	EPO; JPO;	
		177.	DERWENT;	
			IBM_TDB	
1_	19	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
1		coated)).clm. and ((metal or gold or silver)	US-PGPUB;	19:40
		near2 (ball or bump)).clm. and ((metal or	EPO; JPO;	10140
			DERWENT;	
		gold or silver) near2 (layer or film or	· ·	
		foil)).clm.	IBM_TDB	0004/00/00
-	4	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)).clm. and ((metal or gold or silver)	US-PGPUB;	19:40
		near2 (ball or bump)).clm. and ((metal or	EPO; JPO;	
		gold or silver) near2 (layer or film or	DERWENT;	
		foil)).clm. and (board or pcb).clm.	IBM_TDB	
-	43	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)).clm. and ((metal or gold or silver)	US-PGPUB;	19:41
		near2 (ball or bump)) and ((metal or gold or	EPO; JPO;	
		silver) near2 (layer or film or foil)) and	DERWENT;	
	<u> </u>	(board or pcb)	IBM_TDB	
-	252	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:41
		(ball or bump)) and ((metal or gold or silver)	EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb)	IBM_TDB	
_	53	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:41
		(ball or bump)) and ((metal or gold or silver)	EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb) and resin.clm. and (bump or ball).clm.	IBM_TDB	
1_	38	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
-	] 30	coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:41
		(ball or bump)) and ((metal or gold or silver)	•	15:41
			EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb) and resin.clm. and (bump or ball).clm.	IBM_TDB	
		and (bump or ball).ab.		
-	12	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:42
	]	(ball or bump)) and ((metal or gold or silver)	EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb) and resin.clm. and (bump or ball).clm.	IBM_TDB	
L		and (bump or ball).ab. and resin.ab.		

		I		
-	38	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:43
		(ball or bump)) and ((metal or gold or silver)	EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb) and resin.clm. and (bump or ball).clm.	IBM_TDB	
		and (bump or ball).ab. and (board or pcb)		
-	26	((bump or ball) near2 (coat or coating or	USPAT;	2004/02/20
		coated)) and ((metal or gold or silver) near2	US-PGPUB;	19:44
		(ball or bump)) and ((metal or gold or silver)	EPO; JPO;	
		near2 (layer or film or foil)) and (board or	DERWENT;	
		pcb) and resin.clm. and (bump or ball).clm.	IBM_TDB	
		and (bump or ball).ab. and (board or pcb)	_	
		and adhesive		
_	35	(US-6294316-\$ or US-5908317-\$ or	USPAT;	2004/02/20
		US-6259159-\$ or US-6255740-\$ or	US-PGPUB;	19:45
		US-6054171-\$ or US-5641113-\$ or	JPO;	13.40
		US-6165885-\$ or US-6181569-\$ or	DERWENT	
			DERMENI	
		US-5998861-\$ or US-5956605-\$ or		
		US-5891795-\$ or US-5600180-\$ or		
		US-5591941-\$ or US-6245490-\$ or		
		US-6063647-\$ or US-5426850-\$ or		
		US-5873161-\$ or US-6352881-\$ or		
		US-5808360-\$ or US-6222279-\$ or		
		US-6043564-\$ or US-6008071-\$ or		
		US-5866475-\$ or US-6448633-\$ or		
		US-6475896-\$ or US-6255737-\$).did. or		
		(US-6212768-\$ or US-6428393-\$ or		
		US-6643923-\$ or US-6091141-\$).did. or		
		(US-20010050434-\$ or US-20010003656-\$ or		
		US-20020022301-\$).did. or		
		(JP-2000216522-\$).did. or		
		(US-5075965-\$).did.		
-	1	(US-3512051-\$).did.	USOCR	2004/02/20
				19:45
-	4500	(resin near (coat or coating or coated)).clm.	USPAT;	2004/02/20
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	19:51
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<u>-</u>	9	((bump or ball) near2 (resin near (coat or	USPAT;	2004/02/20
		coating or coated))).clm.	US-PGPUB;	19:51
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<u> </u>	5	((bump or ball) near2 (resin near (coat or	USPAT;	2004/02/20
-	9	, , , , , , , , , , , , , , , , , , , ,	•	
		coating or coated))).clm. and adhesive	US-PGPUB;	19:52
			EPO; JPO;	
			DERWENT;	
L			IBM_TDB	

•	12	((bump or ball) near5 (resin near (coat or	USPAT;	2004/02/20
		coating or coated))).clm. and adhesive	US-PGPUB;	19:52
			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
-	73	((bump or ball) near5 (resin near (coat or	USPAT;	2004/02/20
		coating or coated))) and adhesive	US-PGPUB;	19:52
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	21	((bump or ball) near5 (resin near (coat or	USPAT;	2004/02/20
		coating or coated))) and adhesive and	US-PGPUB;	19:53
		((metal or gold or silver) near2 (bump or	EPO; JPO;	
		ball))	DERWENT;	
			IBM_TDB	